

DZ2S068C0L

Silicon epitaxial planar type

For ESD protection
Bi-directional type

■ Features

- High ESD
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: GH

■ Packaging

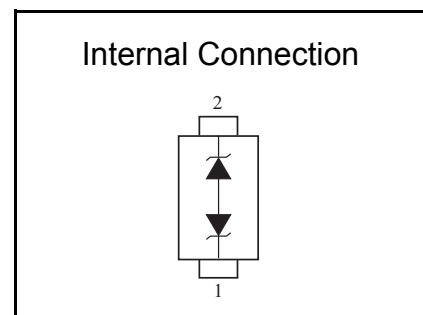
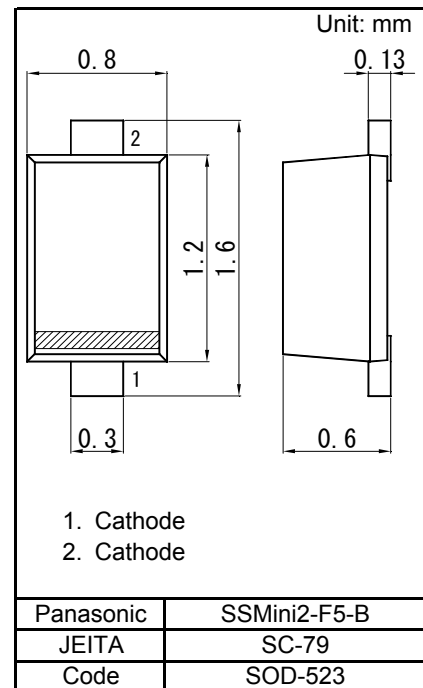
Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Total power dissipation ^{*1}	PT	150	mW
Electrostatic discharge ^{*2}	ESD	±15	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm)
Solder in (0.8 mm × 0.6 mm)

*2 Test method : IEC61000_4_2
(C = 150 pF, R = 330 Ω, Contact discharge : 10 times)



■ Electrical Characteristics Ta = 25 °C ± 3 °C

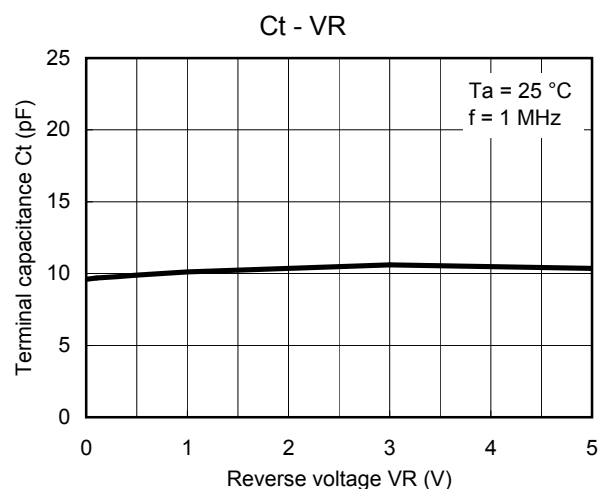
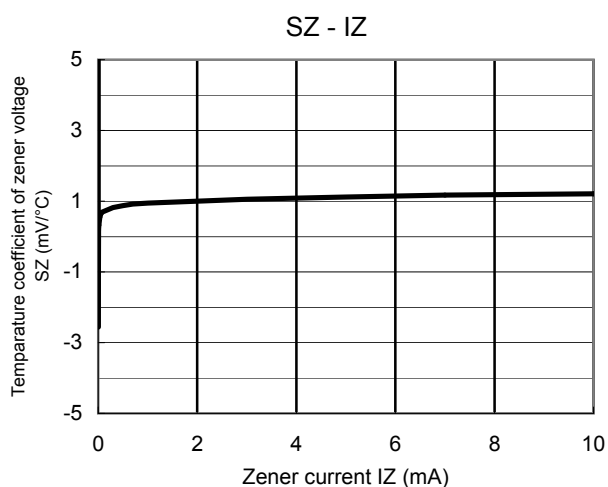
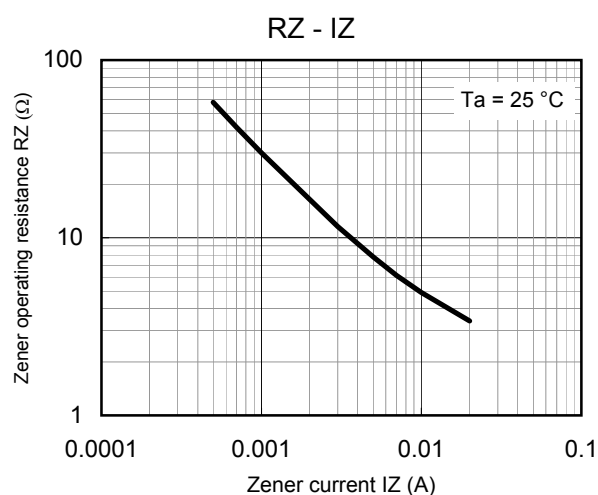
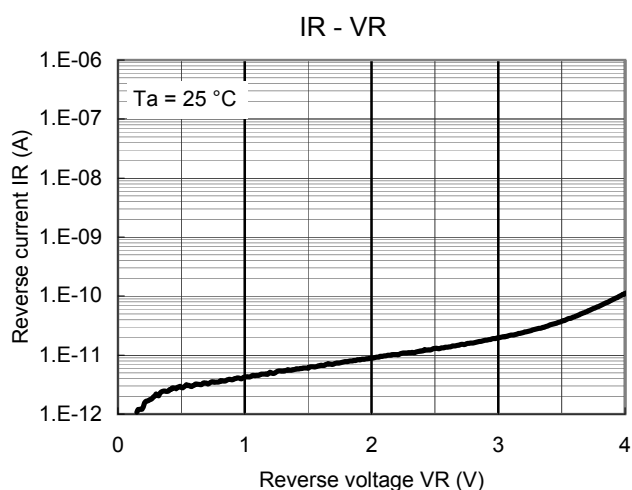
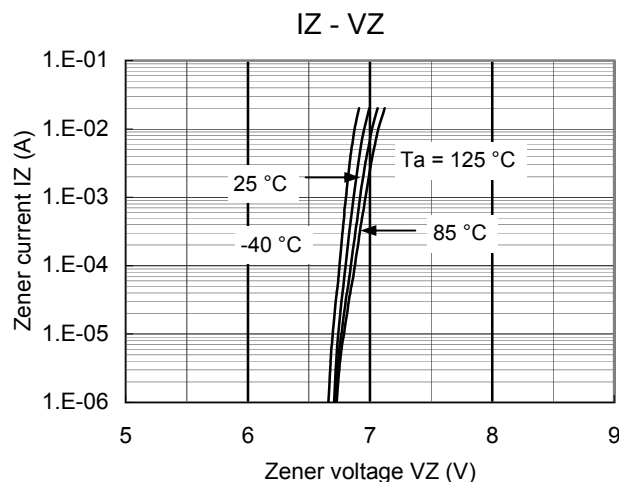
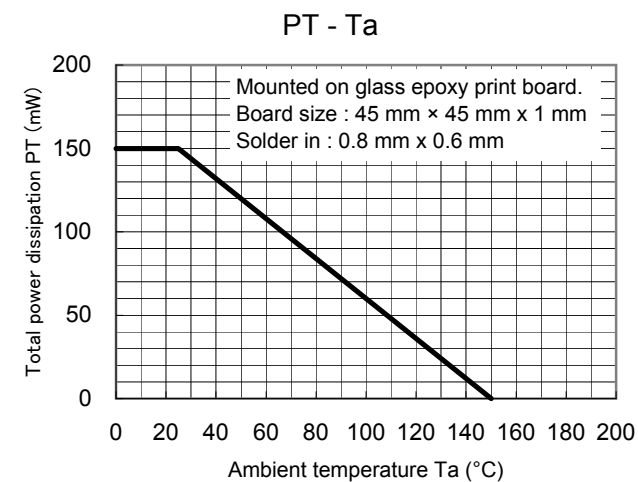
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage ^{*1, *2}	VZ	IZ = 5 mA	6.50		7.50	V
Zener operating resistance	RZ	IZ = 5 mA			20	Ω
Reverse current	IR	VR = 4.0 V			50	nA
Terminal capacitance	Ct	VR = 0 V, f = 1MHz		15.0		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

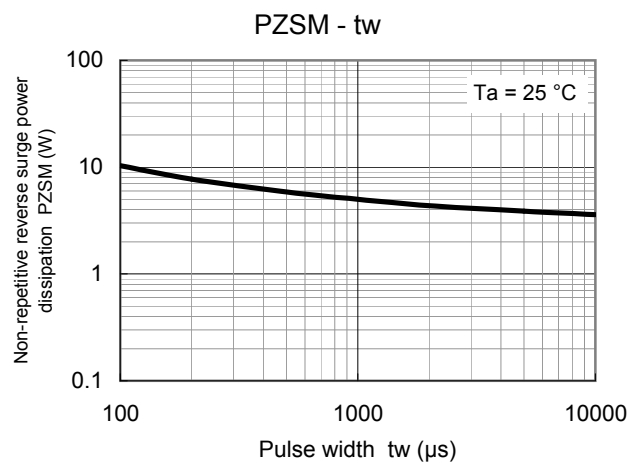
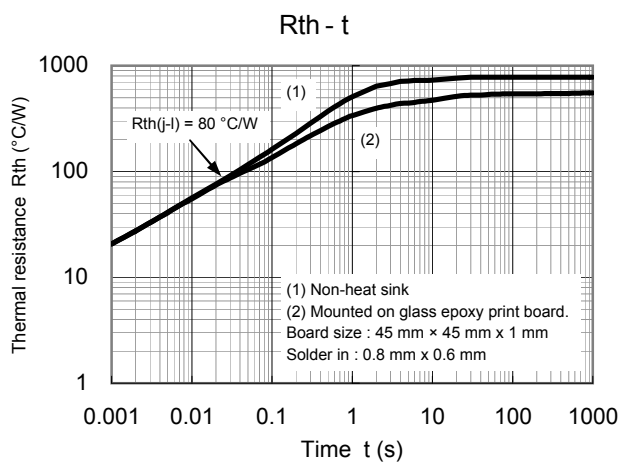
2. *1 The temperature must be controlled 25 °C for VZ measurement.
VZ value measured at other temperature must be adjusted to VZ (25 °C).

*2 VZ guaranteed 20 ms after current flow

Technical Data (reference)

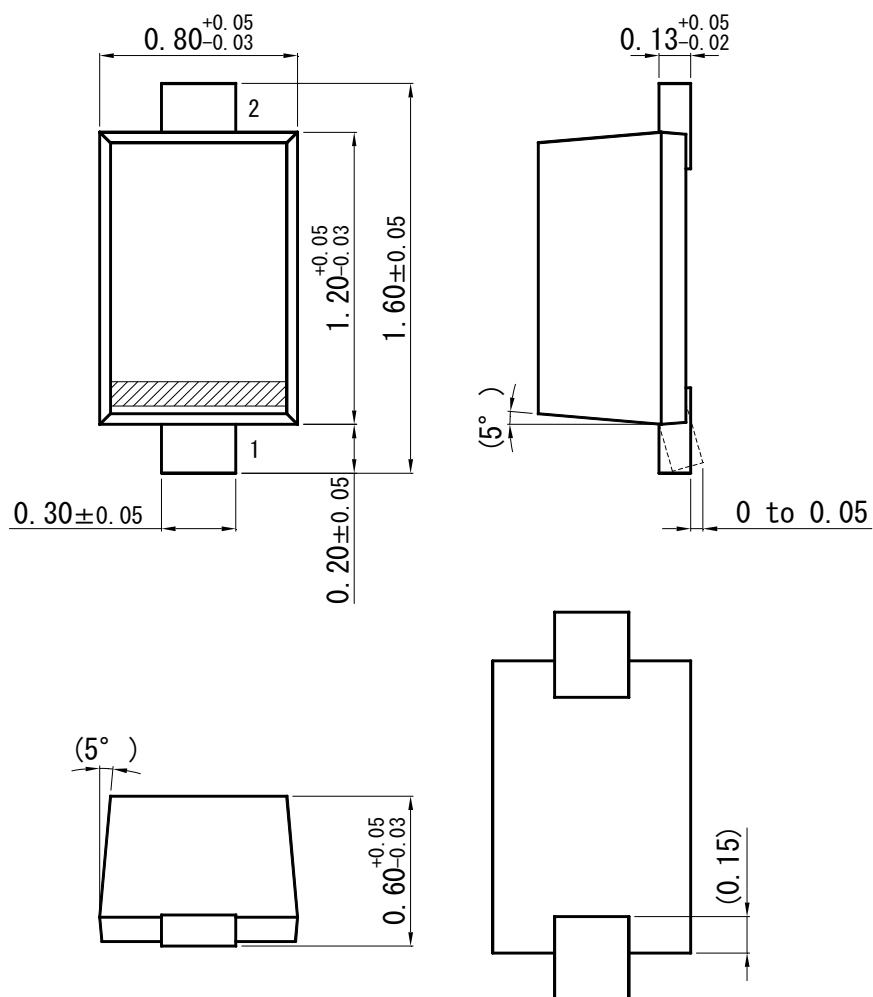


Technical Data (reference)

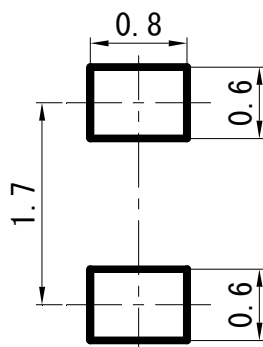


SSMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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